SS36L

SMCG Plastic-Encapsulate Diodes

Schottky Rectifier

Features

- I_O 3A
- VRRM 60V
- High surge current capability
- Polarity: Color band denotes cathode
- Low Vf

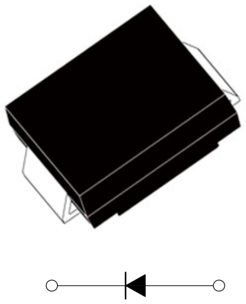
Applications

- Rectifier

Marking

- SS36L

SMCG



Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	SS36L
Repetitive Peak Reverse Voltage	V_{RRM}	V		60
Maximum RMS Voltage	V_{RMS}	V		42
Average Forward Current	$I_{F(AV)}$	A	60Hz Half-sine wave, Resistance load, TL=100℃	3.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz Half-sine wave,1 cycle, Ta=25℃	120
Junction Temperature	T_J	℃		-55~+125
Storage Temperature	T_{STG}	℃		-55~+150

Electrical Characteristics (T_a=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition		SS36L
Peak Forward Voltage	V_F	V	IF=1A IF=2A IF=3A	T_a=25℃	0.34(TYP) 0.40(MAX) 0.38(TYP) 0.42(MAX) 0.42(TYP) 0.45(MAX)
Peak Reverse Current	I_{RRM1}	mA	V_{RM}=V_{RRM}	T_a=25℃	0.05(TYP) 0.3(MAX)
	I_{RRM2}			T_a=100℃	50
Thermal Resistance(Typical)	$R_{\theta J\text{-}A}$	℃/W	Between junction and ambient		47
	$R_{\theta J\text{-}L}$		Between junction and lead		13

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3" x 0.3" (8.0 mm x 8.0 mm) copper pad areas

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

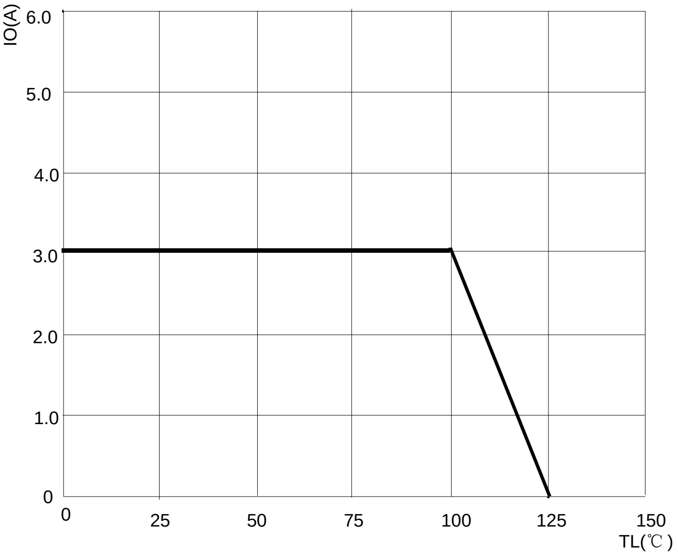


FIG.2: MAXIMUM NON-REPETITIVE FORWARD URGE CURRENT

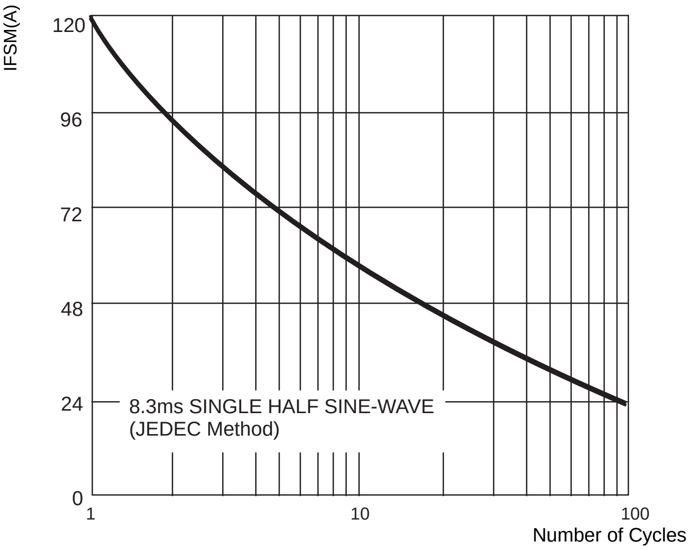


FIG3：Forward Voltage

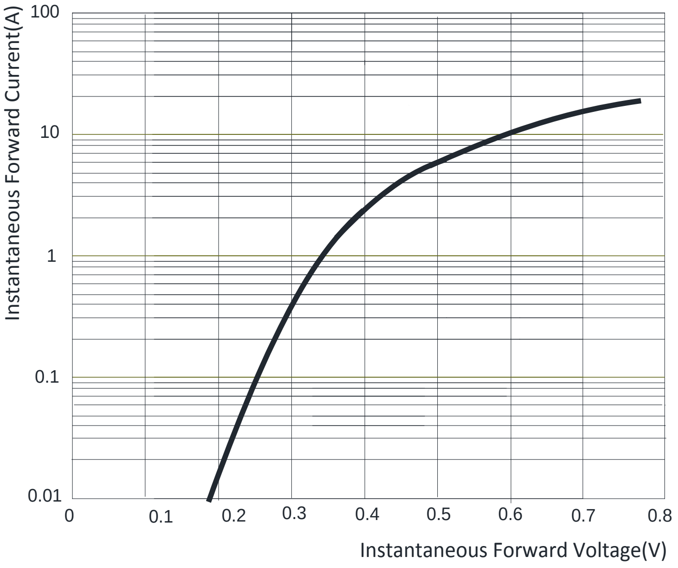
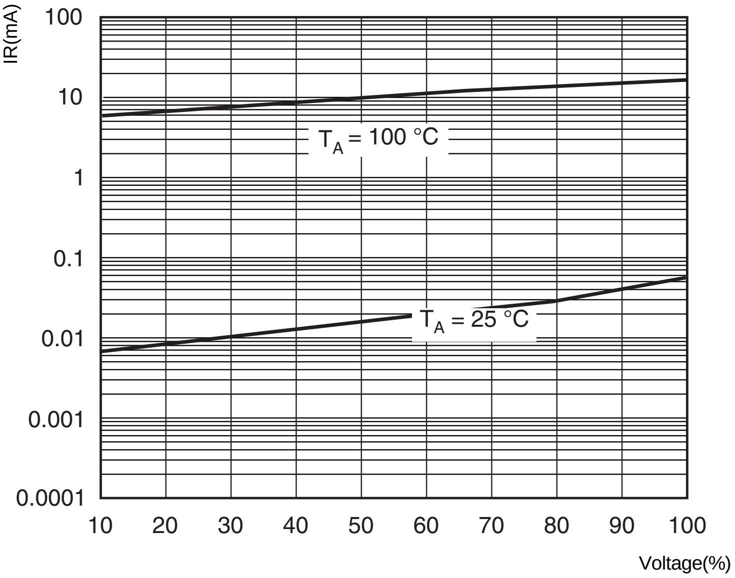
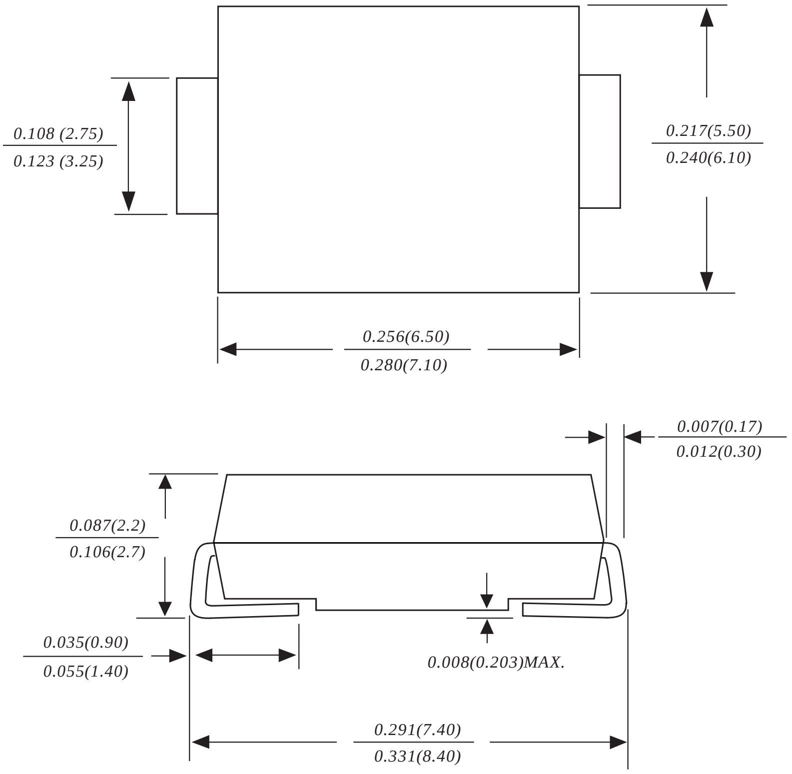


FIG.4：TYPICAL REVERSE CHARACTERISTICS

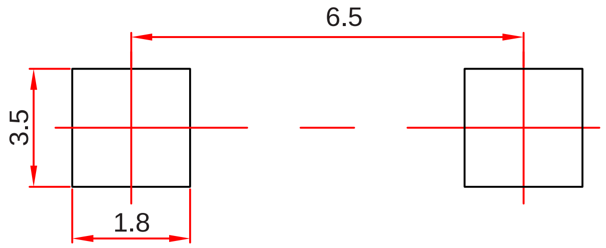


SMCG Package Outline Dimensions



Dimensions in inches and (millimeters)

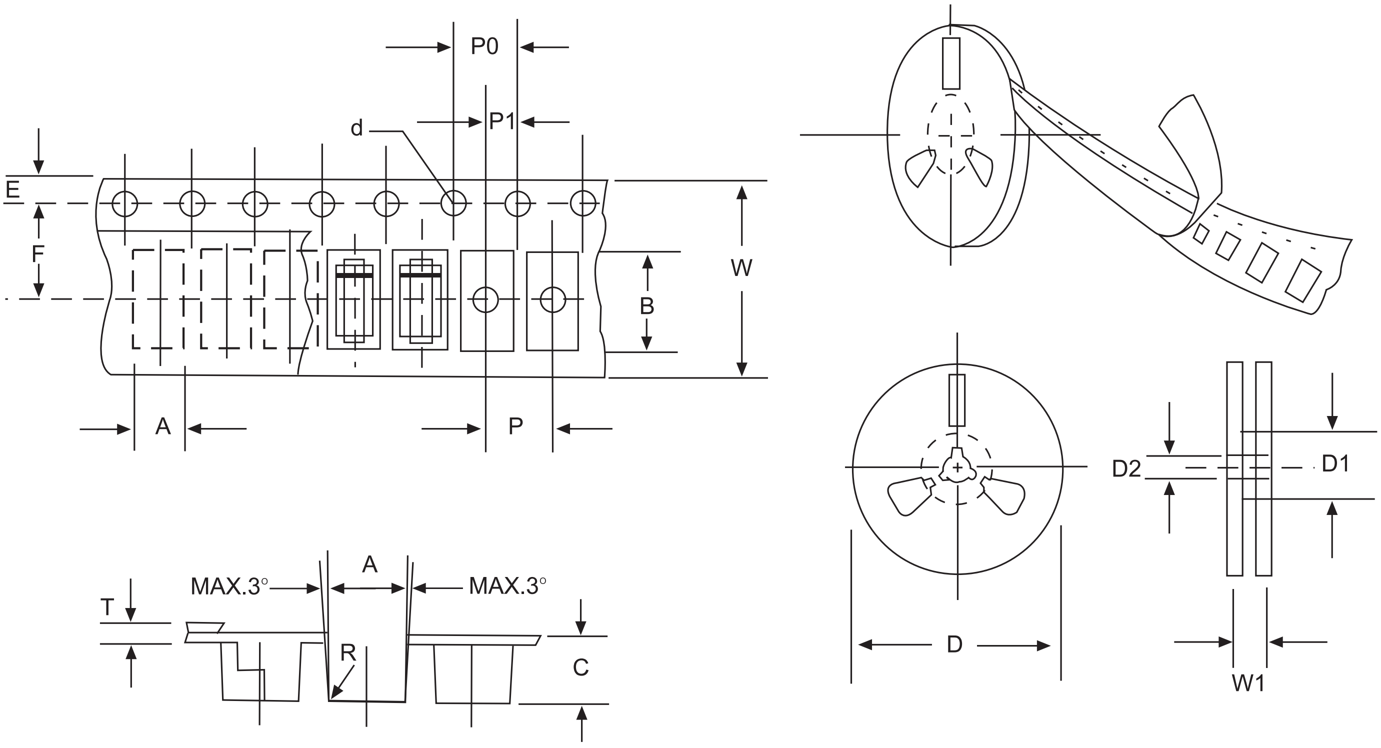
SMCG Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

Reel Taping Specifications For Surface Mount Devices-SMCG



FIG：CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMCG mm(inch)
Carrier width	A	6.05±0.1(0.238±0.004)
Carrier length	B	8.31±0.1(0.327±0.004)
Carrier depth	C	2.70±0.1(0.106±0.004)
Sprocket hole	d	1.55±0.05 (0.061±0.002)
Reel outside diameter	D	330±2.0(13±0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	7.65±0.05(0.301±0.002)
Punch hole pitch	P	8.0±0.1(0.315±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.3±0.1 (0.012±0.004)
Tape width	W	16.0±0.2(0.630±0.008)
Reel width	W1	24.0±2.0(0.945±0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.